

Features

- CMOS Technology
- +/-15 Volt Output Driver Supply Voltage
- Drives Segment or Active Matrix Displays
- 4-Level Gray Scale
- 25MHz Clock Frequency
- Bidirectional Data Transfer
- Selectable Register Length
- 2.7V to 5.5V Logic Supply Voltage
- Cascadable

Applications

- eBooks / eReaders
- Electronic Shelf Labels / Point Of Purchase Displays
- Mobile Phones / Portable Hand Held Devices
- Smart Cards
- Signage

Ordering Information

Part	Description
MX860WB	Gold Bumped Die / Wafer Form
MX860XB	Gold Bumped Die / Waffle Pack
MX860TC	48mm Super Wide Tape Carrier

Description

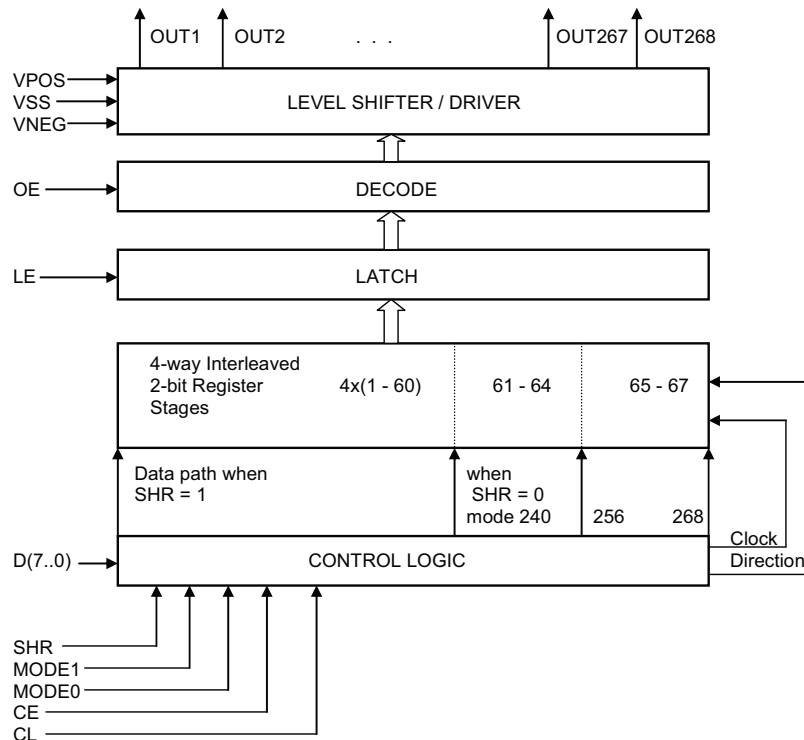
The MX860 is a selectable 240, 256, or 268 bit long; 2-bit wide; serial-input parallel-output digital shift register with level conversion on each parallel output. Level conversion converts the 2 digital bits into V_{POS} , V_{SS} , or V_{NEG} analog output voltages. An 8-bit input bus simultaneously inputs 4 groups of 2 bits each.

The MX860 consists of a selectable length Bidirectional Input Register, Transfer Latch, and 268-bit Level Shifter / Output Driver. Each OUT pin is switched to one of [V_{SS} , V_{POS} , V_{NEG}] according to the D0...D7 logic levels clocked into the MX860, modified by the OE pin.

The MX860 is designed to operate over a temperature range of -40°C to $+85^{\circ}\text{C}$, and is available as Gold Bumped Die in Wafer Form or Waffle Pack, and 48mm Super-Wide Tape Carrier Package.



Figure 1. Functional Block Diagram



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